

# Liquid tin sputtering experiments in the Ion-surface InterAction eXperiment

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*Plasma-Facing Components Meeting, May 9-11, 2005, Princeton, NJ*



# Outline

- Sn sputtering
  - Modeling
  - Experiments
- IIAX modifications/improvements
- Future work
  - Liquid sample sputtering measurements
  - Solid targets for ITER PFC support



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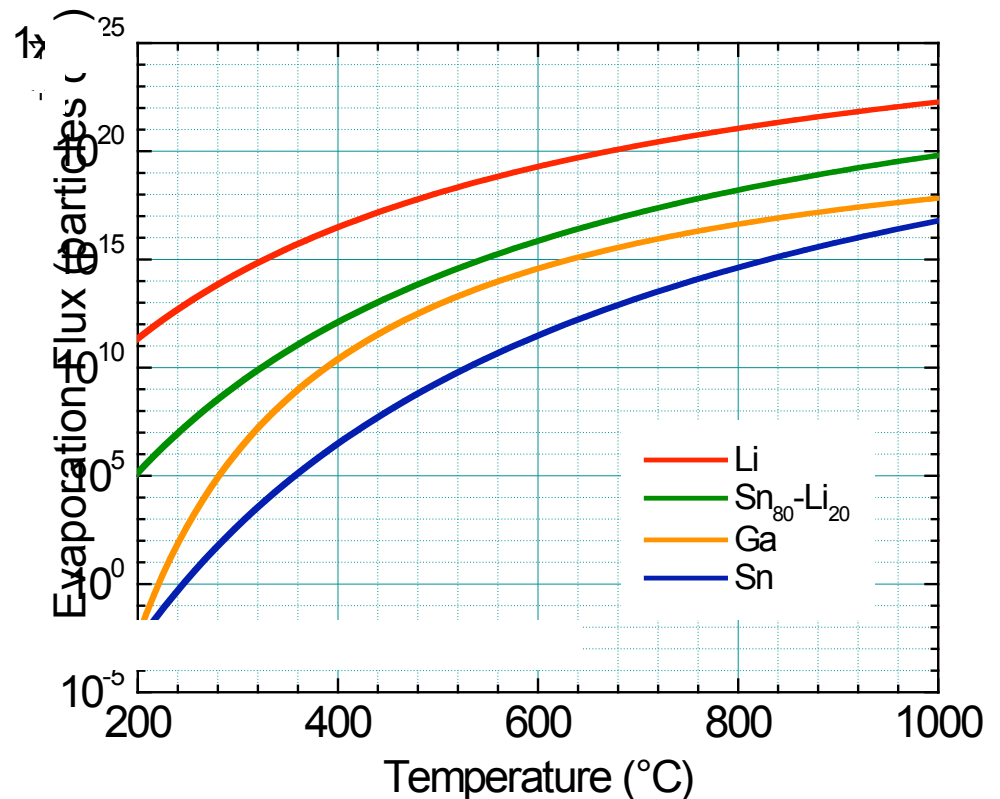
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# Advantage of using liquid Sn

- Sn has an evaporative flux many *orders of magnitude* lower than Li
- Friendly & abundant (cheap!)
- Evaporation curves based on theory by [1] and fits from [2] and [3].



[1] Y. Waseda, S. Ueno, K.T. Jacob, J. Mat. Sci. Let, 8, (1989) 857-861.

[2] M.A. Abdou, A. Ying, N.B. Morley et al., APEX Interim Report Report No. UCLA-ENG-99-206, (1999).

[3] I.A. Sheka, I.S. Chaus, T.T. Mityureva, *The Chemistry of Gallium*, (1966), Elsevier, Amsterdam.

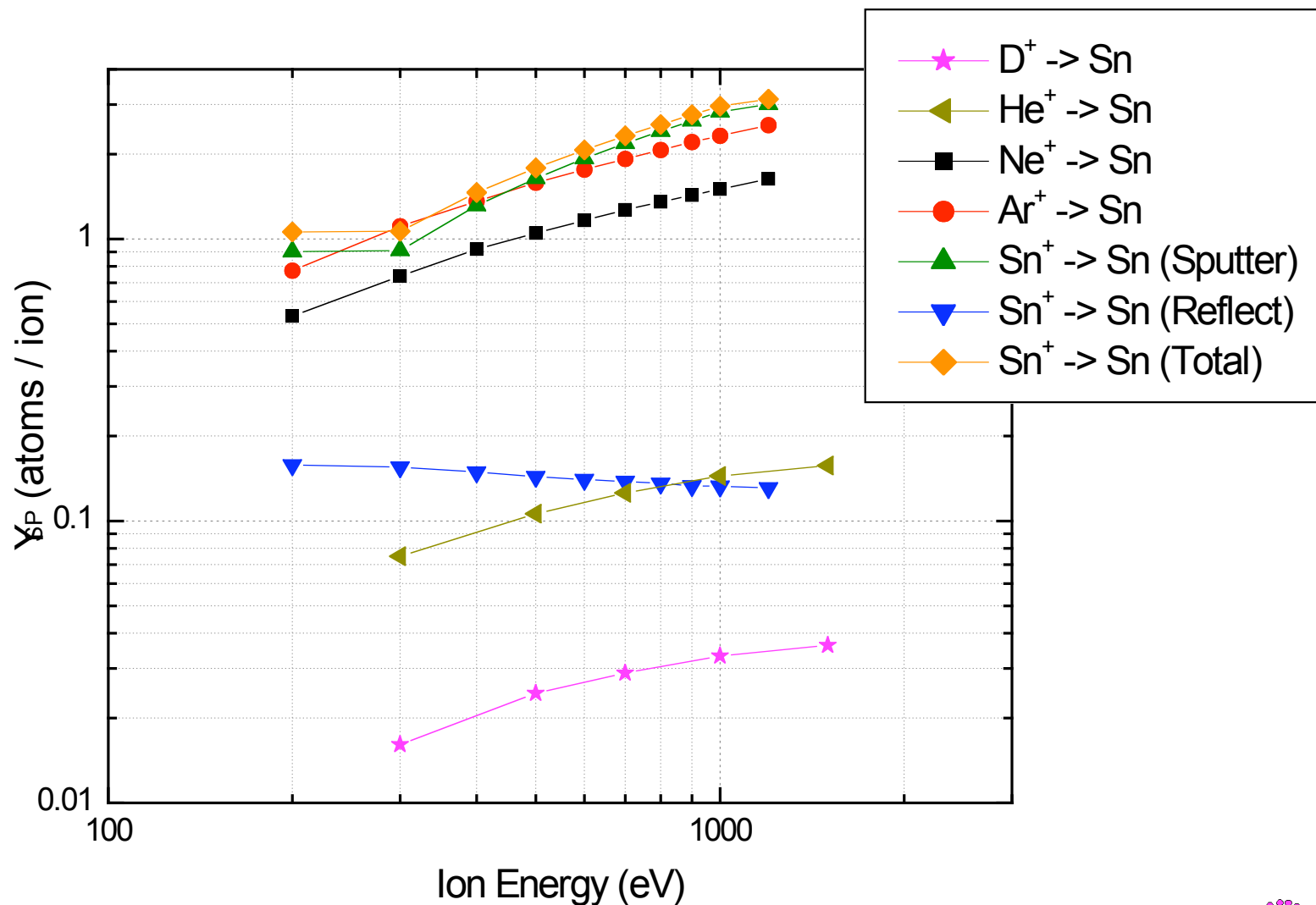


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# VFTRIM Simulation Results for 45° incidence on solid Sn



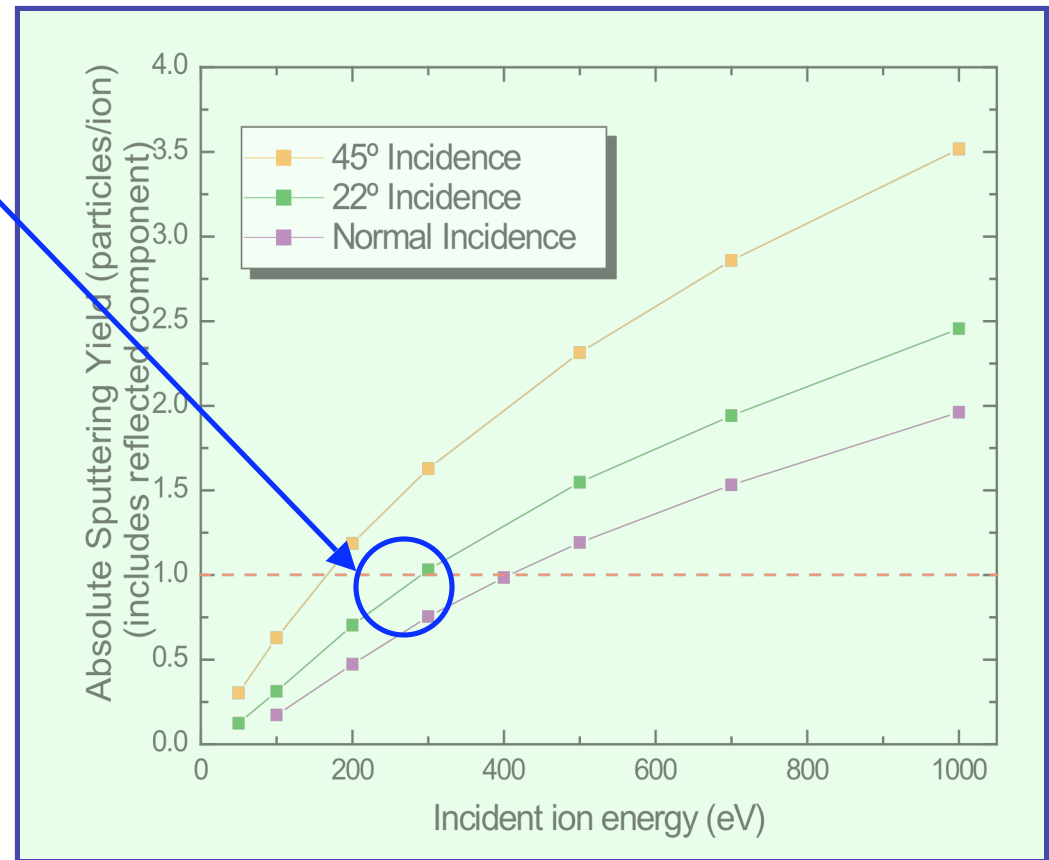
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# VFTRIM Simulations of Sn self-sputtering

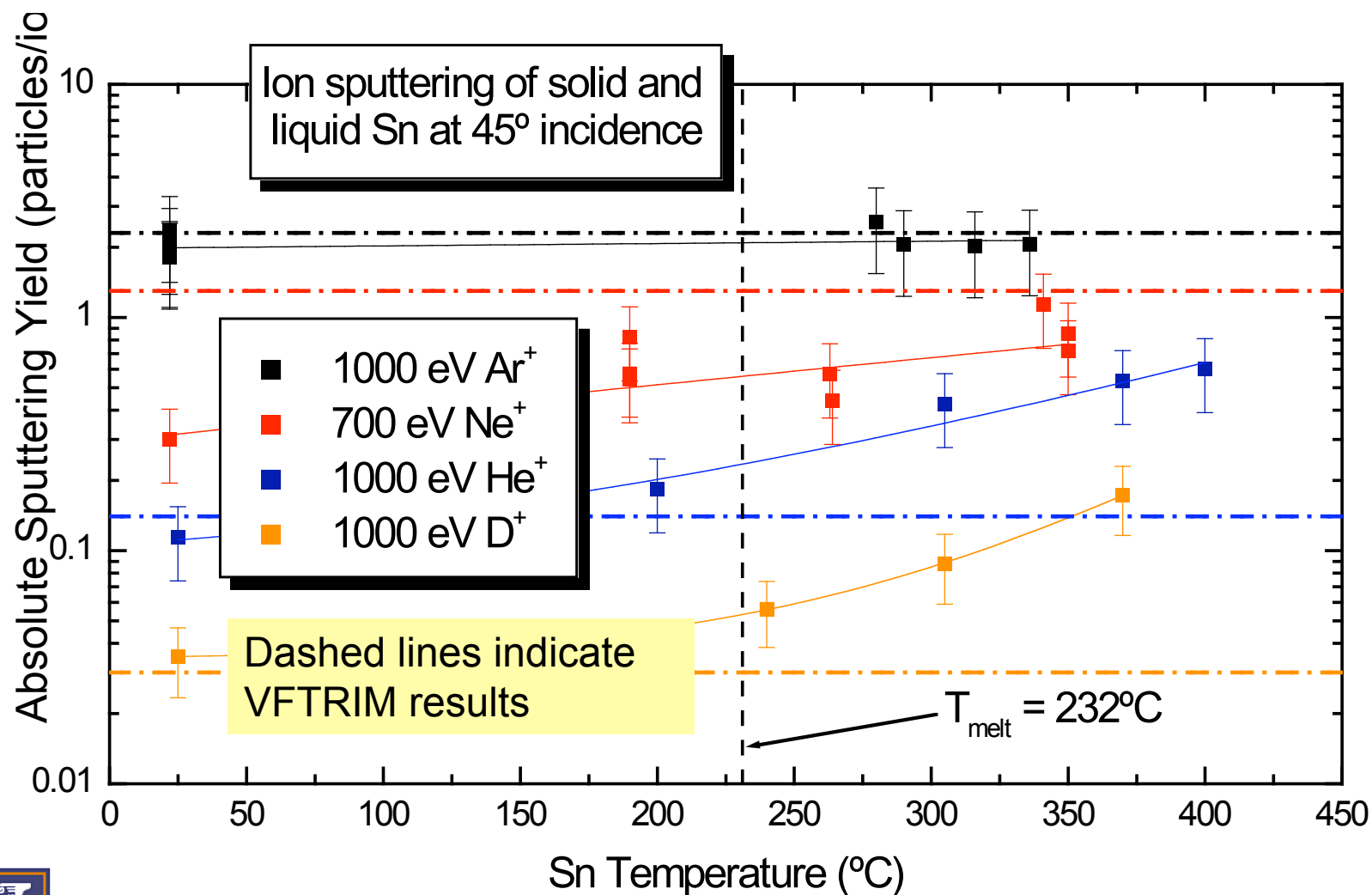
- Sn ions are predicted to have a mean incident angle of  $22^\circ$  and an average energy of 270 eV <sup>[1]</sup> for an ARIES-AT configuration with a liquid Sn divertor
- Thus, equally important is the reduction from decreasing the angle of incidence
- Normal-incidence runs may be performed in the future to complement the oblique work done here
- $D^+$  sputtering of liquid lithium was shown to have a drastic (10 to 1000 fold) increase as a result of increasing the temperature



[1] Brooks, J.N. Fus. Eng. Des. **60** (2002) 515-526.



# Sn sputtering results from 4 species



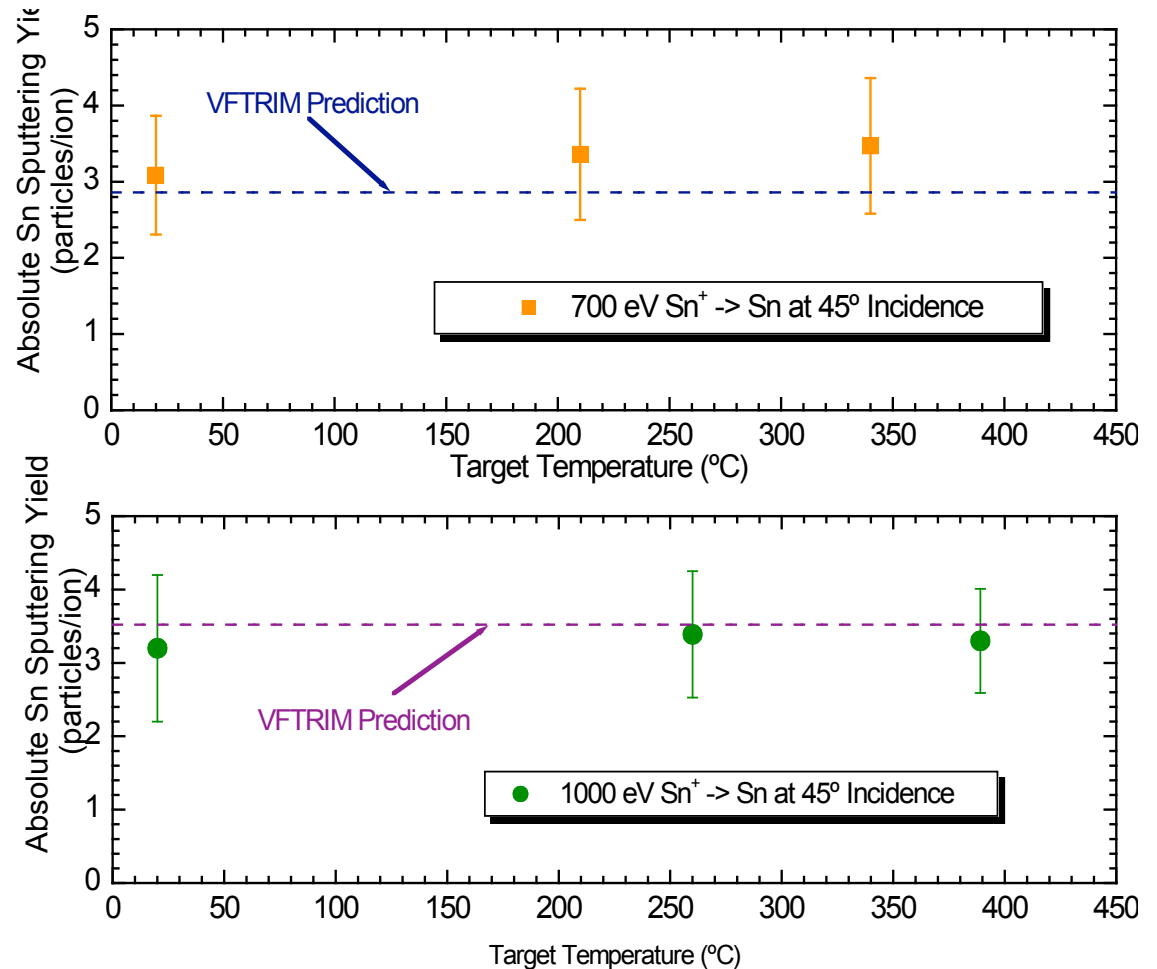
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# Sn self-sputtering measurements

- Early data indicate that Sn self-sputtering is also not significantly enhanced by temperature at least up to 400°C
- These results are similar to those for both Ne<sup>+</sup> and Ar<sup>+</sup> sputtering of Sn (from a temperature enhancement perspective)
- Important to note that higher temperatures may still yet show temperature-enhanced properties



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# Recent improvements

- Data analysis
  - Using VFTRIM “data” of sputtered particle angular distributions to help calculate how much of the ejected material intersects our monitoring crystal
- Hardware upgrades
  - Ion beam system
    - Neutral filter
    - Vertical steering near target
  - Target and QCM system
    - High temperature ability



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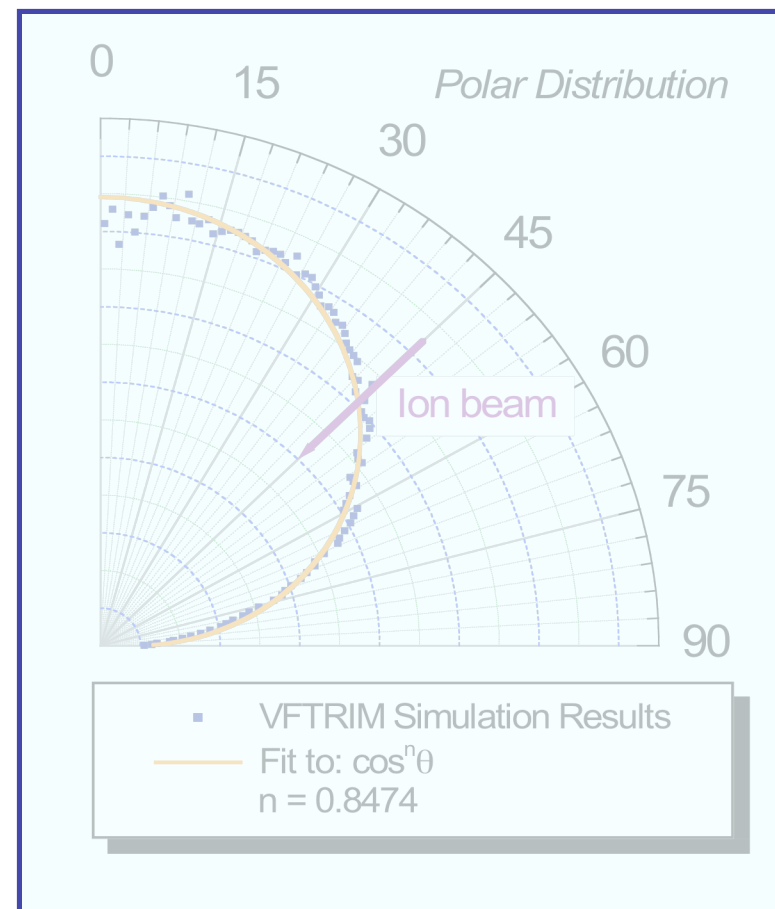
# Improved estimate of “geometric factor”: 1

## In general...

- This “geometric factor” is just an integral over the QCO crystal surface that estimates what fraction of the sputtered material strikes (but not necessarily sticks to) the crystal
- VFTRIM simulations are now performed for each ion-target combination to generate sputtered particle distribution “data” to input into the computation of this geometric factor

## (Polar angle)

- $A$  and  $n$  are fit such that  $A \cdot \cos^n \theta$  fits the VFTRIM polar “data”
- Previously assumed  $\cos^1 \theta$  polar distribution – This correction of  $n$  made little difference in the final result



1000 eV  $\text{Sn}^+ \rightarrow \text{Sn}$   
at  $45^\circ$  incidence

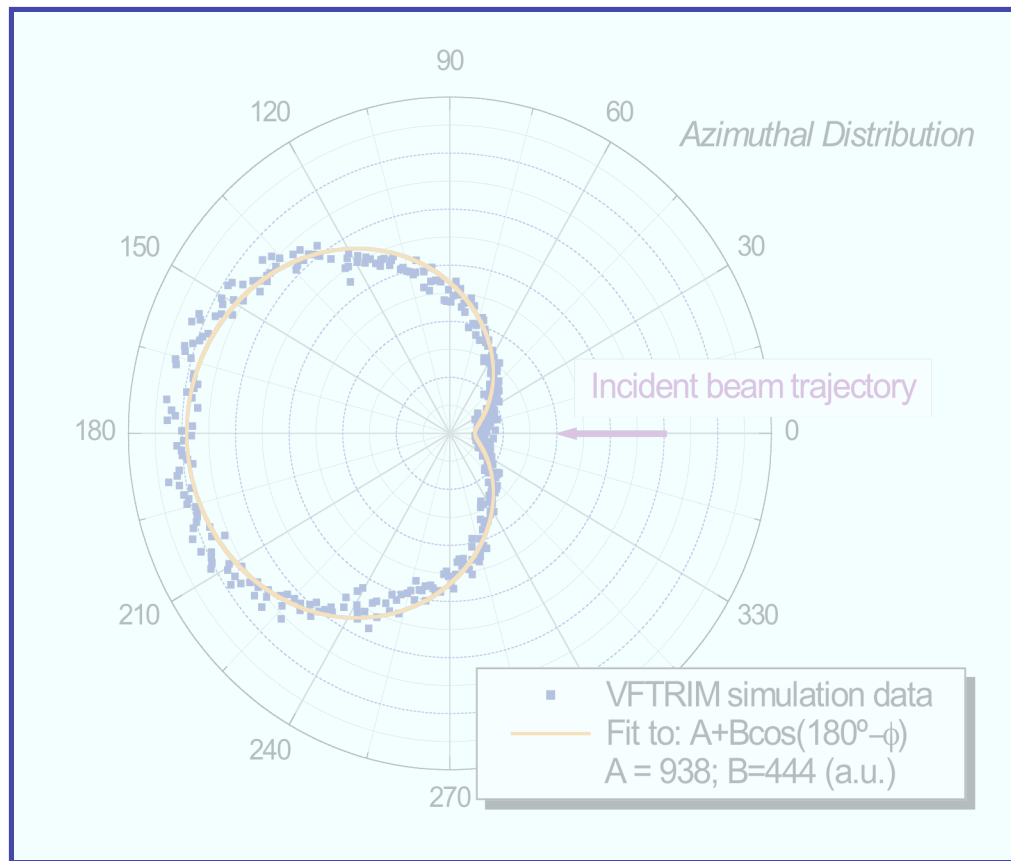


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## Improved estimate of “geometric factor”: 2



(Azimuthal angle)

- Previously assumed azimuthal isotropy
- Significant anisotropy due to oblique incidence
- Parameters  $A$  and  $B$  are varied using  $A + B \cdot \cos(\phi - \pi)$  to fit VFTRIM azimuthal distribution “data”

(NOTE: This function is just a guess that fits most data sets well and so doesn't necessarily have a physical interpretation)

1000 eV  $\text{Sn}^+ \rightarrow \text{Sn}$   
at  $45^\circ$  incidence



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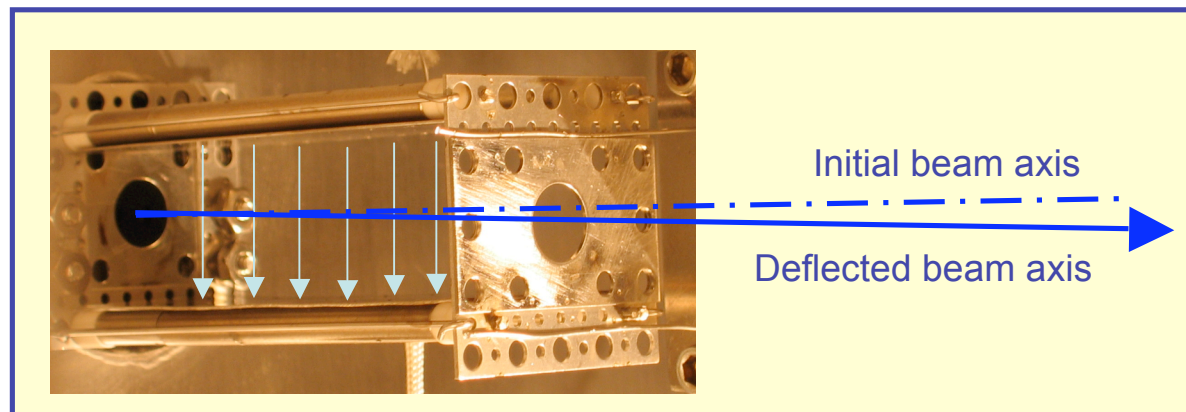
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# Ion beam system modification

## Neutral filter installation

- Installed horizontal deflection plates to make 3° bend to filter neutrals
  - Previously relied on Wien filter  $\underline{E}$ -field to bend beam followed by 10 – 15 cm of 3.5-cm diameter tubing (along unbent beam axis)
  - Now, horizontal deflection for neutral filtering is performed after entering the main chamber to minimize neutral component
  - Unfortunately, this has degraded beam performance (as expected)



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# Prior target temperature was limited

- Two factors...
  - Poor thermal considerations in target/heater holder design limited target to  $\sim 550^{\circ}\text{C}$
  - Above  $\sim 420^{\circ}\text{C}$ , the QCM units would fail due to being close to the hot target without active cooling
- Recent hardware upgrades to allow high temperature measurement
  - Repaired QCM head for electrically-isolated water cooling
  - Installation of new target holder
  - Goal: Reach  $1000^{\circ}\text{C}$  (Heater rated for  $1200^{\circ}\text{C}$ )



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# Modification to QCM head: Electrically-isolated water cooling

- Benefits:
  - Greatly improved crystal stability (better signal to noise ratio) at all temperatures
  - Able to exceed 870°C without crystal failure with no apparent limit as of yet (heater power limit should be ~1100°C)
  - Maintaining the same crystal temperature for all target temperatures
  - Use of a ceramic break and deionized water maintains electrical isolation
- Drawbacks:
  - Greatly reduced mobility of QCM head due to stiff “flexible” water lines
  - Marginally degraded base pressure due to use of Swagelok fittings (low 8’s versus mid 9’s on a good day)



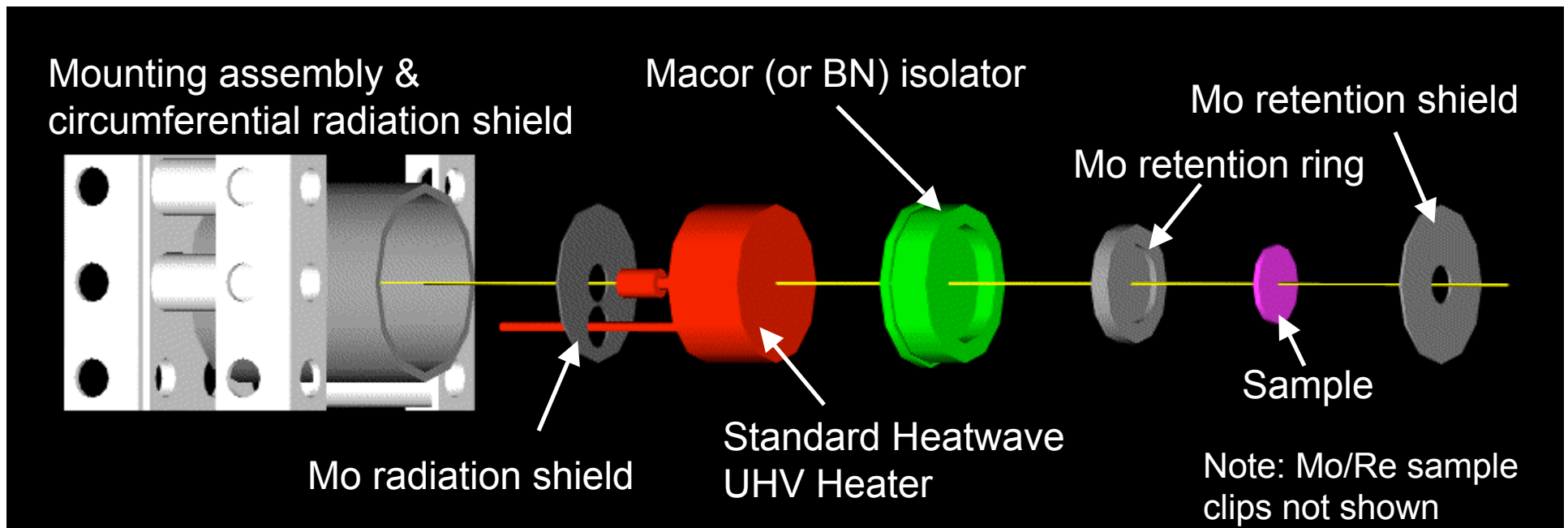
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# Heater & liquid sample holder redesign

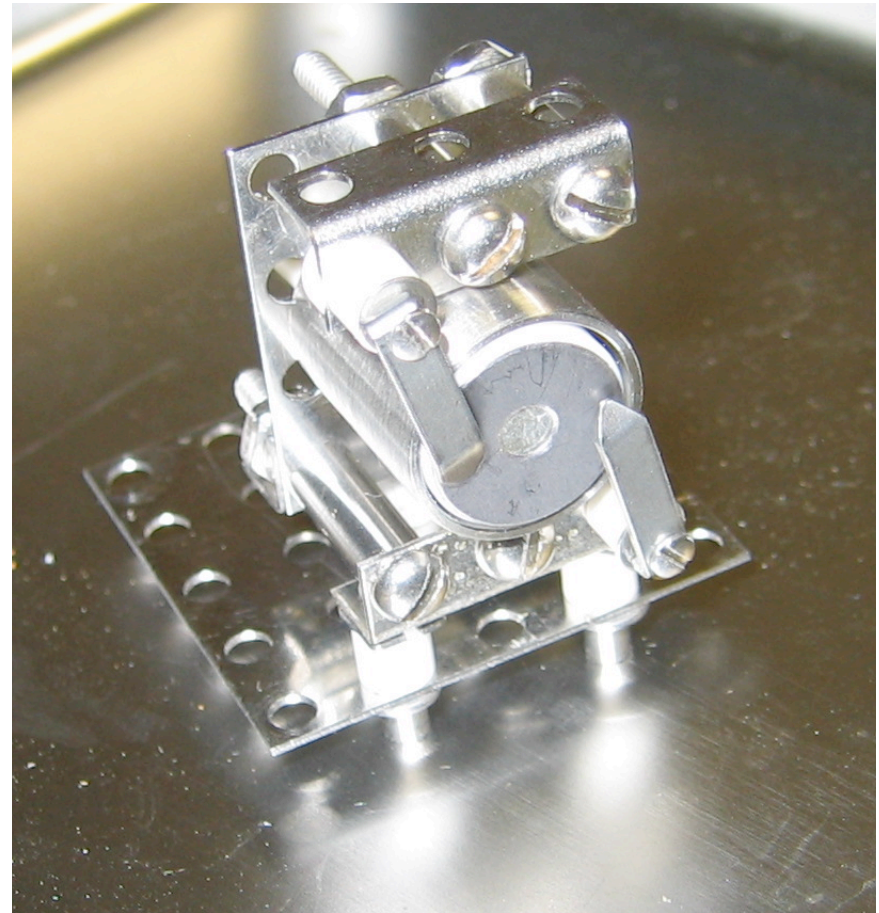
- Thermal considerations
  - Minimized thermal contact between heater/target components and mounting hardware
  - Radiation shield around circumference (SS) and behind (Mo) heater to minimize radiative losses





# New sample holder construction

- Currently, only one assembly 'hard' mounted
- Goal: Several interchangeable sample assemblies
- Quick assembly replacement (through 6" CF port)
- Two samples mounted with others ready to minimize down-time
- Need:
  - Design & construction time
  - Feedthrough
  - UHV-grade plugs

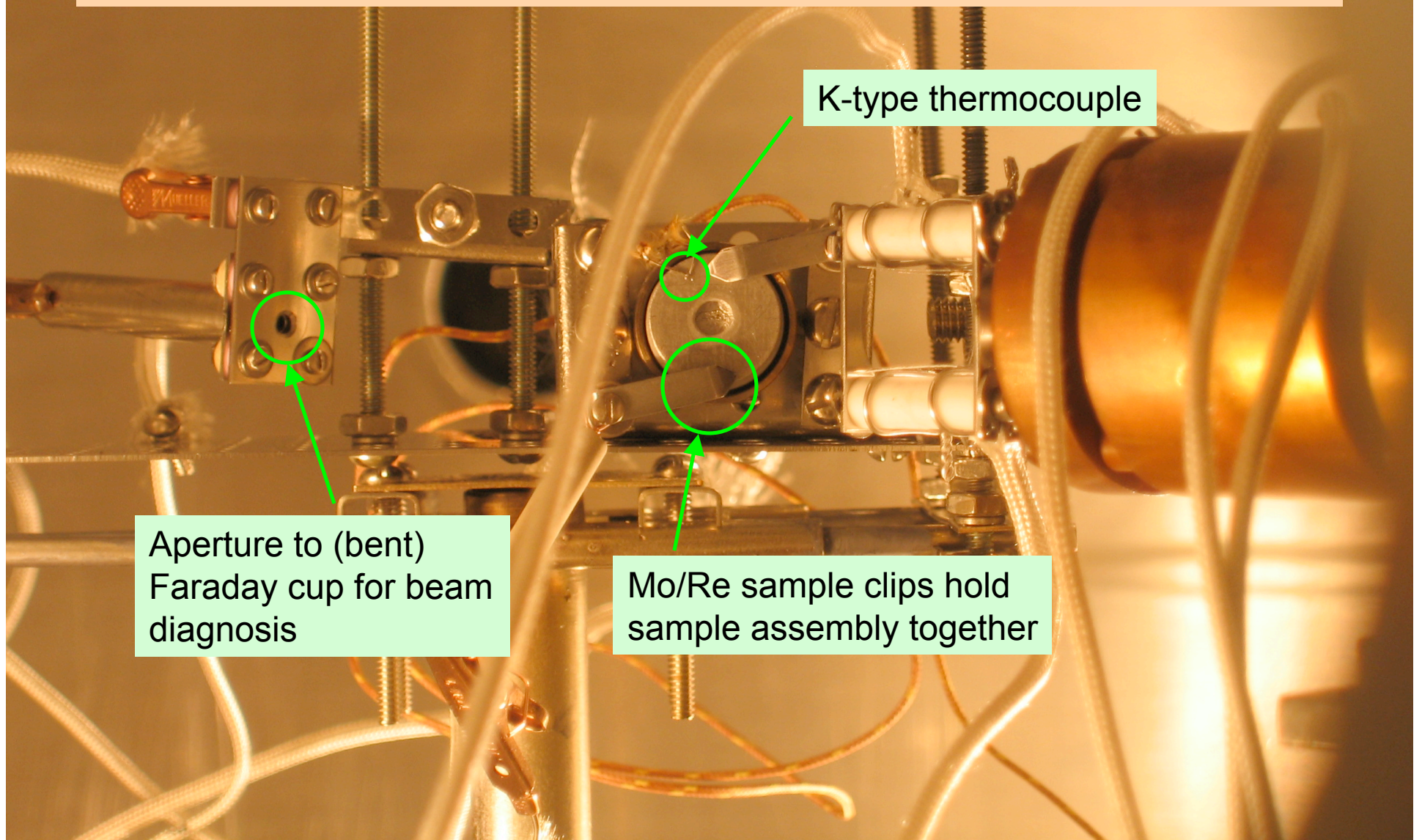


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# New sample holder in place



K-type thermocouple

Aperture to (bent)  
Faraday cup for beam  
diagnosis

Mo/Re sample clips hold  
sample assembly together



## New sample holder in use

- Presently, we're limited by the heater power circuit to  $\sim 870^{\circ}\text{C}$  but reaching  $1100^{\circ}\text{C}$  is achievable assuming  $T^4$  scaling (has shown to be pessimistic so far)
- Some of this sample spilled out, but was otherwise well-behaved and showed a beautifully-reflective surface

# Summary of modifications

- With improved data analysis techniques and an improved ion beam system, our data quality is improved
- To date, hardware limitations have kept our sample temperatures at or below 400°C; since a Sn divertor's evaporation-limited temperature limit is estimated to be 1200°C<sup>[1]</sup>, higher temperature (and lower energy) measurements are needed
- IIAX hardware upgrade should allow sample temperature of at least 1100°C

[1] Brooks, J.N., *Modeling of sputtering erosion/redeposition – status and implications for fusion design*. Fus. Eng. Des., **60** (2002) p515-526.

# Future Work

- Near-term:
  - *Focus on light ion ( $\text{He}^+$  &  $\text{D}^+$ ) sputtering of liquid Sn at higher temperatures – up to  $1000^\circ\text{C}$*
  - *Return to heavy ion sputtering ( $\text{Ne}^+$ ,  $\text{Ar}^+$ , and/or  $\text{Sn}^+$ )*
  - *Reduce ion energies used (ideally to 100-200 eV with use of decelerator)*
- Longer term:
  - *Temp. dep sputtering of liquid Sn & Ga*
  - *Model apparent mass-dependence of temperature-enhanced sputtering*
  - *$\text{Li}^+$  or  $\text{Sn}^+$  sputtering of Mo & LM-coated Mo*
  - *Measurement of the ionized fraction of sputtered material of PFC*
  - *Mixed **solid** material sputtering relevant to ITER (W, Be, C, etc.)*



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